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Elizabeth A. Dudek

Typed or Printed Name of Person Sending Paper or Fee

Elizabeth A. Dudek

January 30, 2007

Signature

Date

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the application of)	
)	
Peter Gravesen, et al.)	Examiner: Octavia L. Davis
)	
Title:)	
TACTILE SENSOR ELEMENT AND)	Art Unit: 2855
SENSOR ARRAY)	
)	Confirmation No. 3290
Serial No.: 10/538,260)	
)	
Filed On: June 9, 2005)	(Our Docket No. . 6495-0108WOUS)

Hartford, Connecticut, January 30, 2007

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

S I R:

Applicant(s) submits herewith Form PTO/SB/08A identifying patents, publications or other information of which they are aware, which they believe may be material to the examination of this application and in respect of which there may be a duty to disclose.

The filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made (37 CFR 1.97(g)), an admission that the information cited is, or is considered to be, material to patentability, or that no other material information exists.

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The filing of this Information Disclosure Statement shall not be construed as an admission against interest in any manner. Notice of January 9, 1992, 1135 O.G. 13-25, at 25.

Under 37 CFR 1.97 (b)

☐ This Information Disclosure Statement is being filed within three months of the filing date of the application, or the date of entry into the national stage of an international application, or before the mailing date of a first Office Action on the merits, whichever event occurs last.

Under 37 CFR 1.97 (c)

☒ This Information Disclosure Statement is being filed *after* three months of the filing date of this national application, or the date of entry into the national stage as set forth in §1.491 in an international application, or after the mailing date of the first Office Action on the merits, whichever event occurred last, but *before* the mailing date of either a final action under §1.113 or a notice of allowance under §1.311, whichever occurs first.

☐ A certification as specified in 37 CFR 1.97(e) is set forth below or

☒ Fee as set forth in 37 CFR 1.17(p) (\$180.00).

Under 37 CFR 1.97(d)

☐ This Information Disclosure Statement is being filed *after* a final action under §1.113 or a notice of allowance under §1.311, whichever occurs first, but before, or simultaneously with, the payment of the issue fee. Applicant hereby petitions for the consideration of this Information Disclosure Statement, 37 CFR 1.97(d)(ii). A certification as specified in 37 CFR 1.97(e) is set forth below.

☐ A certification as specified in 37 CFR 1.97(e) is set forth below and

☐ Fee as set forth in 37 CFR 1.17(p) (\$180.00).

CERTIFICATION (37 CFR 1.97(e))

☐ Each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Statement. A copy of the relevant search report is enclosed herewith.

☐ No item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the person signing this certification after making reasonable inquiry, was known to any individual designated in §1.56(c) more than three months prior to the filing of this Statement.

Under 37 CFR 1.98(a)(2)(i)

☒ Because the above-referenced application was filed after June 30, 2003, pursuant to USPTO Notice dated 7/11/2003 ("*Information Disclosure Statements May Be Filed Without Copies of U.S. Patents and Published Applications filed after June*

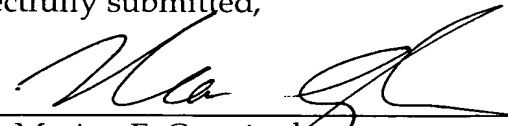
Serial No. 10/538,260
Information Disclosure Statement
Dated: 01/30/2007

30, 2003") Applicant(s) do not provide copies of the U.S. patents identified on the attached PTO/SB/08A form at this time. Should the Examiner require the U.S. patent copies, Applicants respectfully request the Examiner contact Applicants' Representative at the number listed below.

Applicants respectfully request that any deficiencies in the fees be charged to Deposit Order Account No. 13-0235.

Respectfully submitted,

By


Marina F. Cunningham
Registration No. 38,419
Attorney for Applicants

McCormick, Paulding & Huber LLP
CityPlace II, 185 Asylum Street
Hartford, CT 06103-3402
(860) 549-5290



FORM PTO-1449

INFORMATION DISCLOSURE STATEMENT BY APPLICANT(S)

Docket No.: 6495-0108WOUS
 Applicant: Peter Gravesen, et al.
 Title: Tactile Sensor Element and
 Sensor Array

U.S. Serial No.: 10/538,260
 U.S. Filing Date: 06/09/2005
 Group Art Unit: 2855

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<u>Examiner's Initials</u>	<u>Document Number</u>	<u>Date</u>	<u>Country</u>	<u>Translation</u>	
				<u>Yes</u>	<u>No</u>
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EXAMINER

DATE CONSIDERED

EXAMINER:

Initial if citation considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).